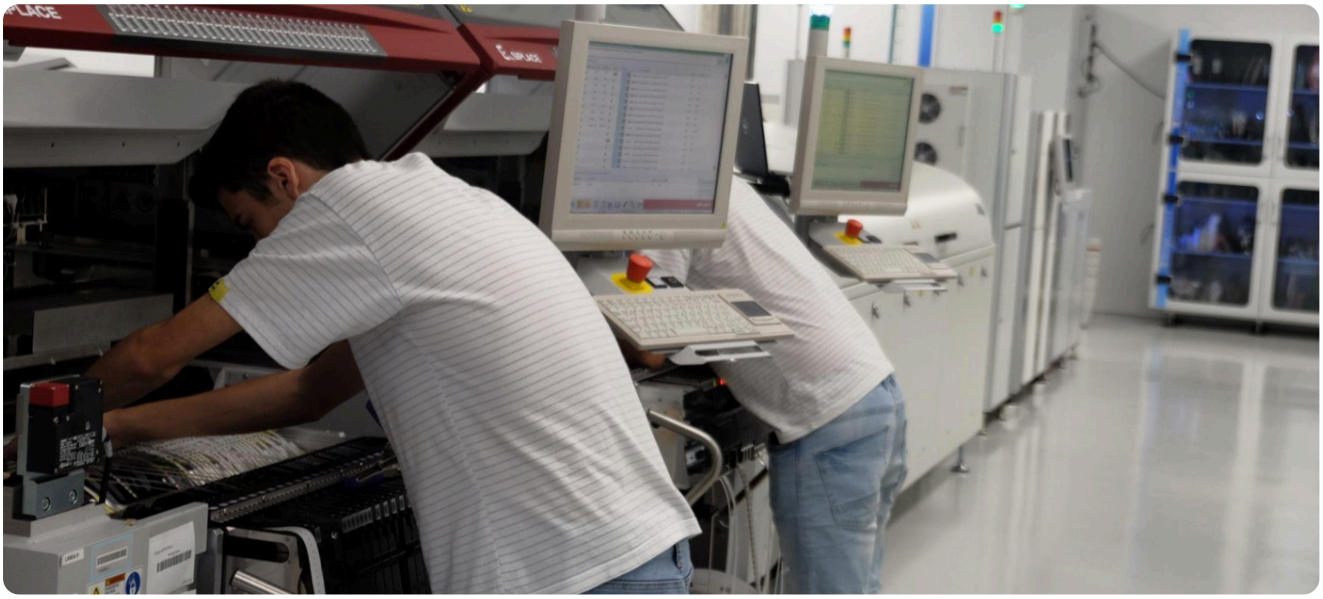
Electronics assembly with inspection and traceability at every step.

Partners in technology

We build PCBAs for third parties, from prototypes to large series, in our own plant in Badalona (Barcelona), with engineering alongside every project.



80,000
placements/h theoretical (20,000–40,000 actual)

400 × 460 mm
maximum panel on the SMT line (minimum 80 × 80 mm)

0201 → BGA 0.4
from 0201 passives to 0.4 mm pitch BGA

100%
of boards inspected by 3D AOI

Certified quality

ISO 9001:2015 · ISO 13485:2016 · IPC-A-610 · RoHS · ESD area · 40% own solar energy

How we work

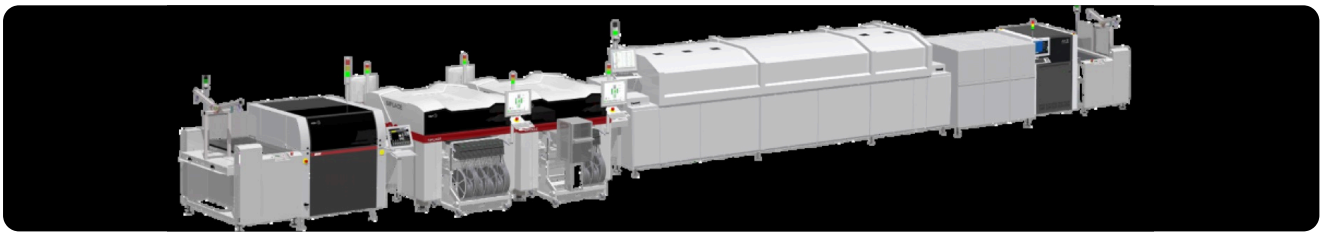
One line, ready for prototypes and series. We assemble SMT and THT in an ESD-protected area, with standardised processes under ISO 9001 and ISO 13485.

Full traceability. Every board carries a QR code: we know which components and lots were placed, when, and which checks it passed.

Engineering alongside. We review your design for manufacturability (DfM) and propose alternatives when a part is scarce.

SMT line

A complete ASM line, from printing to final inspection, with automatic loading and unloading.



Printing	ASM DEK Photon with integrated 2D solder paste inspection (SPI)
Pick & Place	2 × ASM Siplace E: SPEED (12-nozzle head) and FLEX (12 nozzles + PP)
Reflow	SEHO Reflow 2.3, 14 zones (7 + 7), lead-free; Mole MAP profiler
AOI	Omron 3D AOI at line output, with automatic OK / NOK unloading
Handling	Multi Magazine Loader, 4 link conveyors, FIFO buffer and shuttle unloader

Capabilities

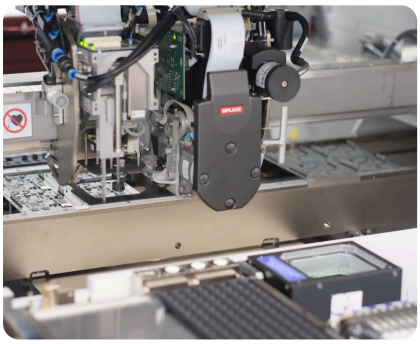
- Components from **0201 to 200 × 125 mm**, up to 50 mm high (01005 with an upgrade)
- **BGA, µBGA, LGA, CSP** at 0.4 / 0.5 / 0.65 / 0.8 mm pitch · **QFN and QFP** at 0.4 mm
- SOT, TSOP, QSOP, VSOP, PLCC, LQFP and LED
- Fine-pitch vision, placement-force and coplanarity control in real time

Feeders and materials

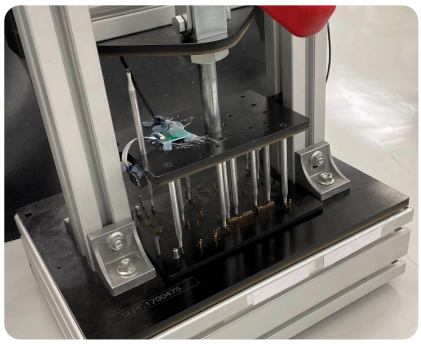
- Reel: 8, 12, 16, 24, 32 and 44 mm
- Stick: 20 slots · Tray: 15 trays
- Interflux and Kester solder pastes
- Two humidity-controlled cabinets (Essegui) and a component drying oven

THT, inspection and test

Selective soldering	ERSA Smartflow 2020, boards up to 508 × 508 mm, spray fluxer and process camera
2D / 3D X-ray	Nordson DAGE Quadra 3 Pro, 70 µm/pixel with X-Plane slicing: BGA, QFN, shorts, PTH fill and counterfeit detection (on request)
3D AOI	Omron, with an offline programming station
ICT and functional test	Custom bed-of-nails fixtures, machined on our own CNC, with a QR reader that logs the results
Flying probe	Subcontracted service (SPEA 4050 S2): parametric ICT without fixtures
Rework	IR6500 infrared BGA station and JBC hot-air station
Protection	Conformal coating and potting







Final assembly and services

- Box build with **torque-controlled screwing**
- **Laser marking** of PCBAs, enclosures and labels
- **Cobot** Universal Robots UR3e assisting operators
- 3D-printed jigs (Ultimaker S5)
- Semi-automatic V-cut depaneling
- **Purchasing, warehousing and picking** of components and product



From design to series, without changing supplier

If you don’t have the design yet, we do that too: schematics and PCB, firmware, Embedded Linux, FPGA, Edge AI and connectivity. What we design, we also build.



Tell us about your project

Send us your BOM, Gerbers and quantities, and we’ll prepare your quote.

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